

ZIITEK ELECTRONIC MATERIAL & TECHNOLOGY CO., LTD

TIF[™]700Z Thermally Conductive Silicone Pads Series

time of the heat-generating electronic components.

TIF[™]700Z Series thermally conductive interface materials are applied to fill the air gaps between the heating elements and the heat dissipation fins or the metal base. Their flexibility and elasticity make them suited to coat very uneven surfaces. Heat can transmit to the metal housing or dissipation plate from the heating elements or even the entire PCB, which effecitly enhances the efficiency and life-

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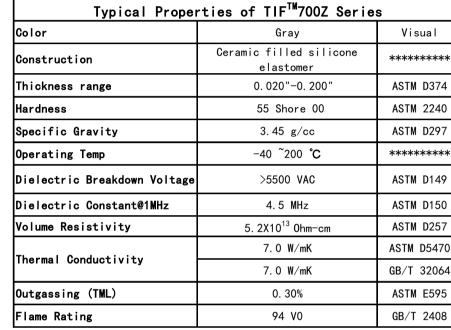


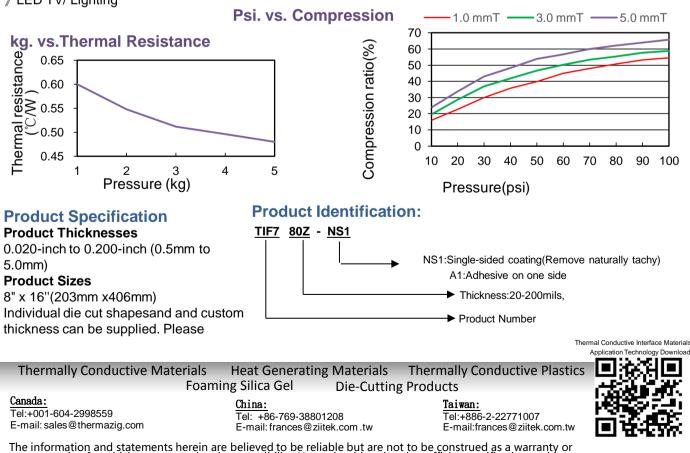
Features

- » Good thermal conductivity: 7.0 W/mK
- » Naturally tacky needing no further adhesive coating
- Soft and Compressible for low stress applications
- » Available in varies thickness

Application

- Cooling components to the chassis of frame
- » Car Battery & Power Supply
- » Charging Pile
- » Graphics Card Thermal Module
- Set Top Box
- » LED TV/ Lighting





The information and statements herein are believed to be reliable but are not to be construed as a warranty or representation for which we assume legal responsibility. Users should undertake sufficient verification and testing to determine the suitability for their own particular purpose of any information or products referred to herein.

http://www.ziitek.com